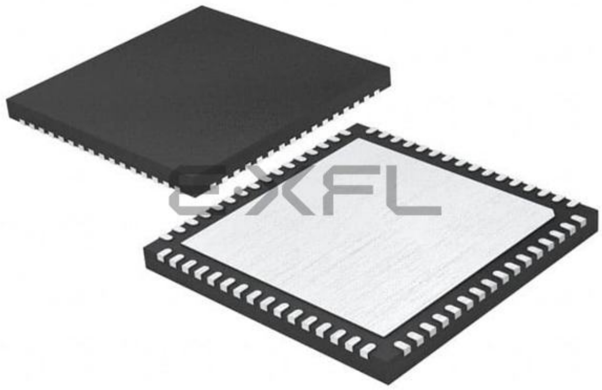
Microchip Technology - PIC24EP512GP206-I/MR Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512gp206-i-mr

FIGURE 2-5: SINGLE-PHASE SYNCHRONOUS BUCK CONVERTER

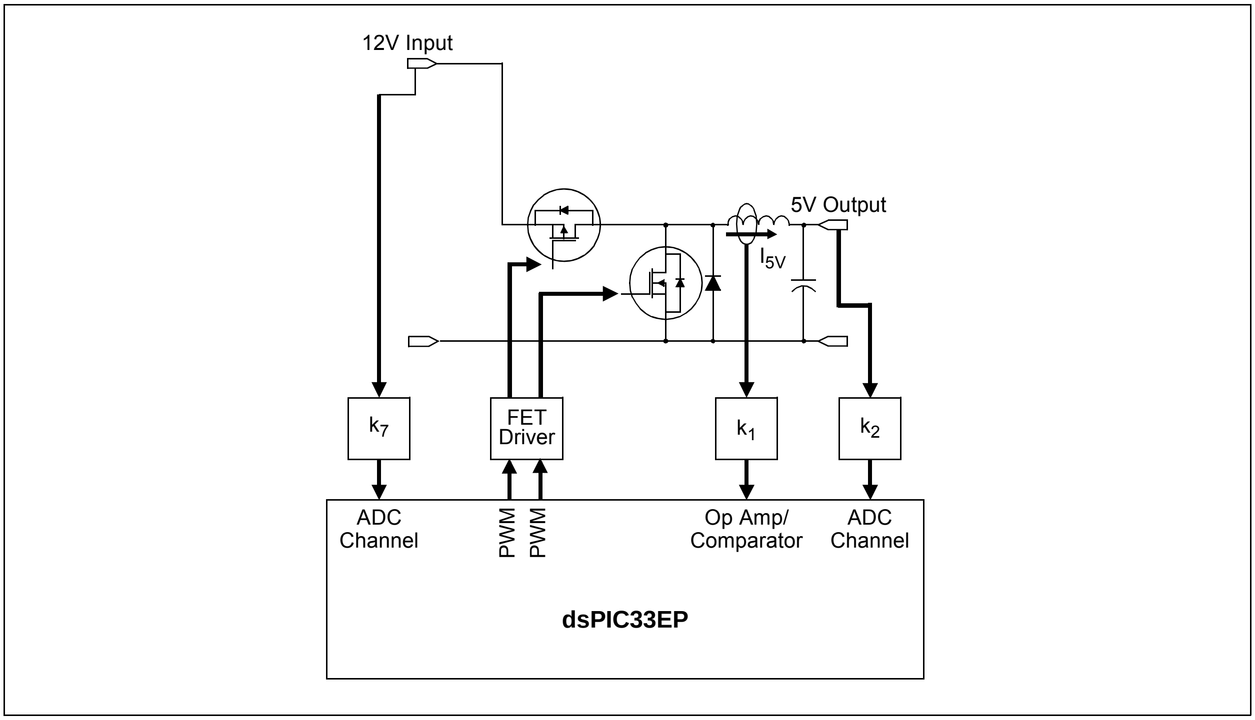
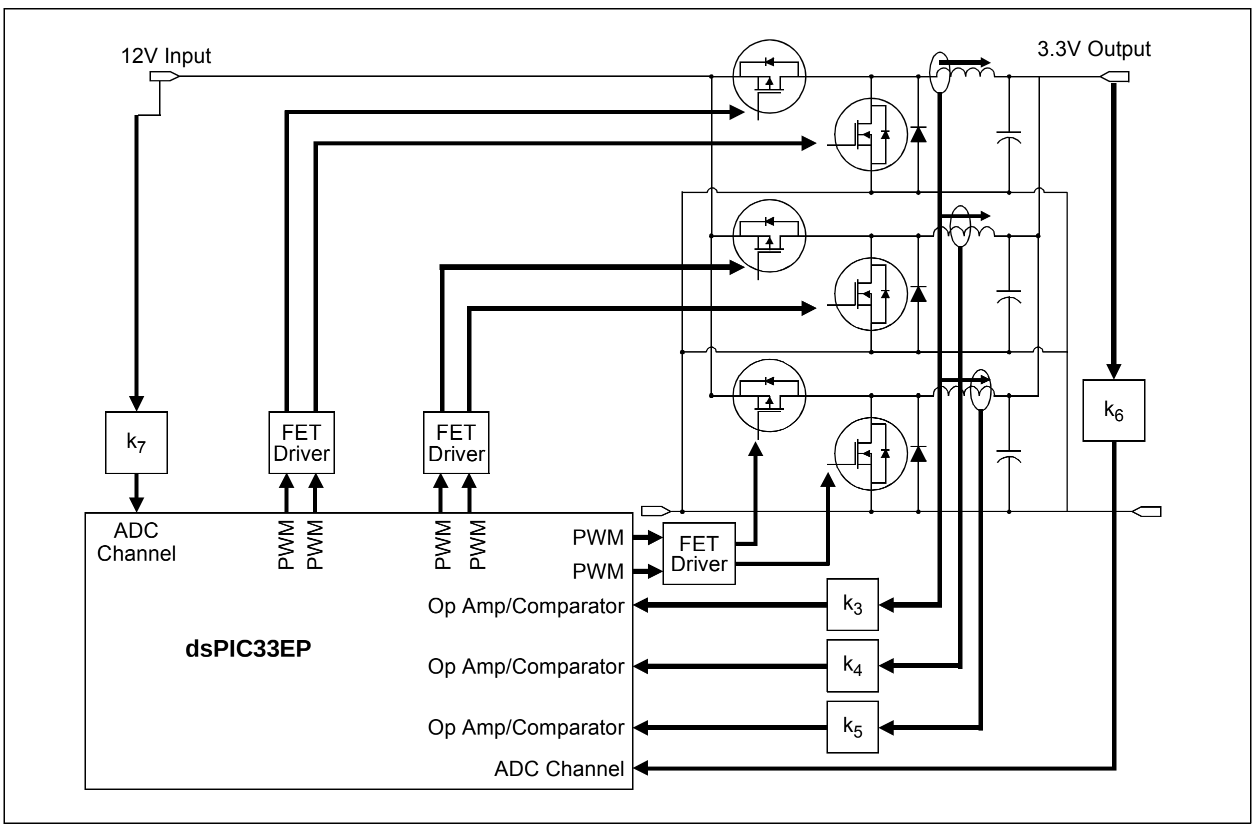


FIGURE 2-6: MULTIPHASE SYNCHRONOUS BUCK CONVERTER



Allocating different Page registers for read and write access allows the architecture to support data movement between different pages in data memory. This is accomplished by setting the DSRPAG register value to the page from which you want to read, and configuring the DSWPAG register to the page to which it needs to be written. Data can also be moved from different PSV to EDS pages, by configuring the DSRPAG and DSWPAG registers to address PSV and EDS space, respectively. The data can be moved between pages by a single instruction.

When an EDS or PSV page overflow or underflow occurs, EA<15> is cleared as a result of the register indirect EA calculation. An overflow or underflow of the EA in the EDS or PSV pages can occur at the page boundaries when:

- The initial address prior to modification addresses an EDS or PSV page
- The EA calculation uses Pre-Modified or Post-Modified Register Indirect Addressing; however, this does not include Register Offset Addressing

In general, when an overflow is detected, the DSxPAG register is incremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. When an underflow is detected, the DSxPAG register is decremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. This creates a linear EDS and PSV address space, but only when using Register Indirect Addressing modes.

Exceptions to the operation described above arise when entering and exiting the boundaries of Page 0, EDS and PSV spaces. Table 4-61 lists the effects of overflow and underflow scenarios at different boundaries.

In the following cases, when overflow or underflow occurs, the EA<15> bit is set and the DSxPAG is not modified; therefore, the EA will wrap to the beginning of the current page:

- Register Indirect with Register Offset Addressing
- Modulo Addressing
- Bit-Reversed Addressing

TABLE 4-61: OVERFLOW AND UNDERFLOW SCENARIOS AT PAGE 0, EDS and PSV SPACE BOUNDARIES(2,3,4)

O/U, R/W	Operation	Before			After		
		DSxPAG	DS EA<15>	Page Description	DSxPAG	DS EA<15>	Page Description
O, Read	`[++Wn]` or `[Wn++]`	DSRPAG = 0x1FF	1	EDS: Last page	DSRPAG = 0x1FF	0	See **Note 1**
O, Read		DSRPAG = 0x2FF	1	PSV: Last lsw page	DSRPAG = 0x300	1	PSV: First MSB page
O, Read		DSRPAG = 0x3FF	1	PSV: Last MSB page	DSRPAG = 0x3FF	0	See **Note 1**
O, Write		DSWPAG = 0x1FF	1	EDS: Last page	DSWPAG = 0x1FF	0	See **Note 1**
U, Read	`[--Wn]` or `[Wn--]`	DSRPAG = 0x001	1	PSV page	DSRPAG = 0x001	0	See **Note 1**
U, Read		DSRPAG = 0x200	1	PSV: First lsw page	DSRPAG = 0x200	0	See **Note 1**
U, Read		DSRPAG = 0x300	1	PSV: First MSB page	DSRPAG = 0x2FF	1	PSV: Last lsw page

Legend: O = Overflow, U = Underflow, R = Read, W = Write

Note 1: The Register Indirect Addressing now addresses a location in the base Data Space (0x0000-0x8000).

2: An EDS access with DSxPAG = 0x000 will generate an address error trap.

3: Only reads from PS are supported using DSRPAG. An attempt to write to PS using DSWPAG will generate an address error trap.

4: Pseudo-Linear Addressing is not supported for large offsets.

4.4.2 EXTENDED X DATA SPACE

The lower portion of the base address space range, between 0x0000 and 0x7FFF, is always accessible regardless of the contents of the Data Space Page registers. It is indirectly addressable through the register indirect instructions. It can be regarded as being located in the default EDS Page 0 (i.e., EDS address range of 0x000000 to 0x007FFF with the base address bit, EA<15> = 0, for this address range). However, Page 0 cannot be accessed through the upper 32 Kbytes, 0x8000 to 0xFFFF, of base Data Space, in combination with DSRPAG = 0x000 or DSWPAG = 0x000. Consequently, DSRPAG and DSWPAG are initialized to 0x001 at Reset.

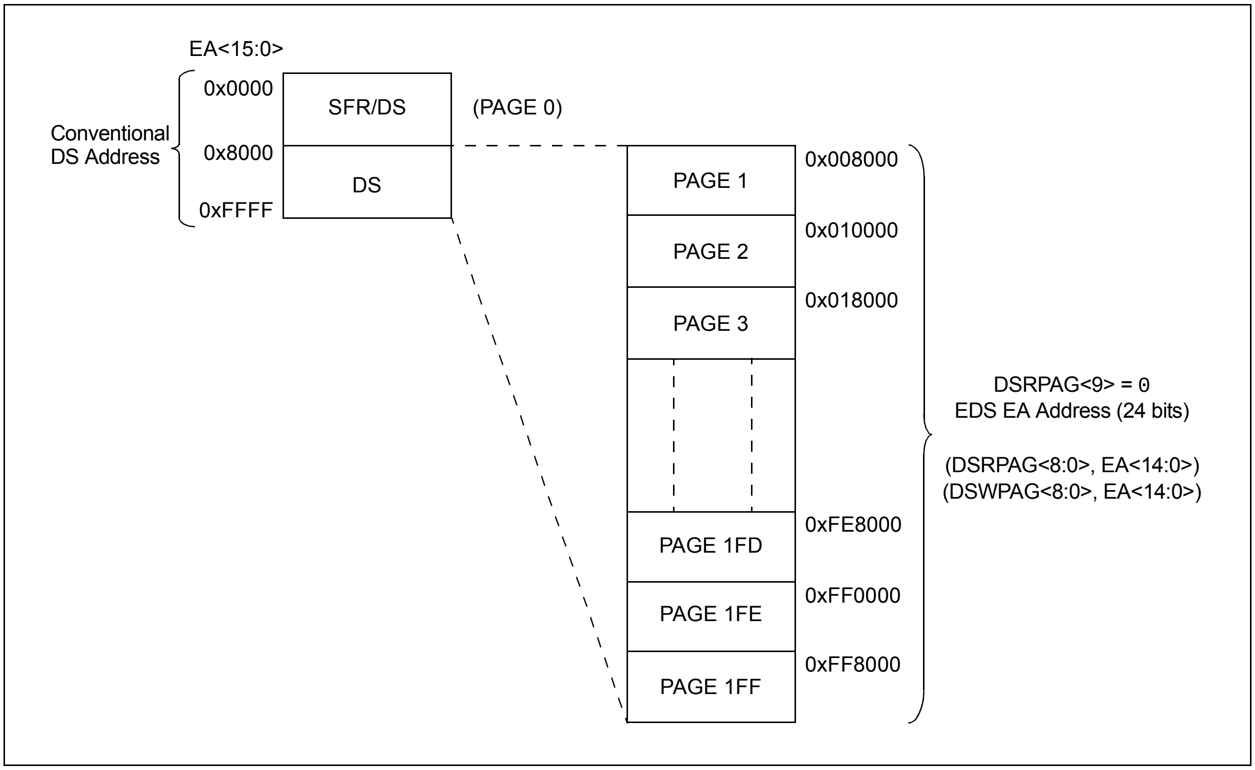
> **Note 1:** DSxPAG should not be used to access Page 0. An EDS access with DSxPAG set to 0x000 will generate an address error trap.
>
> **2:** Clearing the DSxPAG in software has no effect.

The remaining pages, including both EDS and PSV pages, are only accessible using the DSRPAG or DSWPAG registers in combination with the upper 32 Kbytes, 0x8000 to 0xFFFF, of the base address, where base address bit, EA<15> = 1.

For example, when DSRPAG = 0x001 or DSWPAG = 0x001, accesses to the upper 32 Kbytes, 0x8000 to 0xFFFF, of the Data Space will map to the EDS address range of 0x008000 to 0x00FFFF. When DSRPAG = 0x002 or DSWPAG = 0x002, accesses to the upper 32 Kbytes of the Data Space will map to the EDS address range of 0x010000 to 0x017FFF and so on, as shown in the EDS memory map in Figure 4-17.

For more information on the PSV page access using Data Space Page registers, refer to the **"Program Space Visibility from Data Space"** section in **"Program Memory"** (DS70613) of the *"dsPIC33/PIC24 Family Reference Manual"*.

FIGURE 4-17: EDS MEMORY MAP



REGISTER 7-1: SR: CPU STATUS REGISTER[1]

R/W-0	R/W-0	R/W-0	R/W-0	R/C-0	R/C-0	R-0	R/W-0
OA	OB	SA	SB	OAB	SAB	DA	DC
bit 15							bit 8

R/W-0[3]	R/W-0[3]	R/W-0[3]	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL<2:0>[2]			RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’= Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits[2,3]

`111` = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
`110` = CPU Interrupt Priority Level is 6 (14)
`101` = CPU Interrupt Priority Level is 5 (13)
`100` = CPU Interrupt Priority Level is 4 (12)
`011` = CPU Interrupt Priority Level is 3 (11)
`010` = CPU Interrupt Priority Level is 2 (10)
`001` = CPU Interrupt Priority Level is 1 (9)
`000` = CPU Interrupt Priority Level is 0 (8)

Note 1: For complete register details, see Register 3-1.

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = `1`. User interrupts are disabled when IPL<3> = `1`.

3: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = `1`.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
GIE	DISI	SWTRAP	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **GIE:** Global Interrupt Enable bit
1 = Interrupts and associated IE bits are enabled
0 = Interrupts are disabled, but traps are still enabled

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13 **SWTRAP:** Software Trap Status bit
1 = Software trap is enabled
0 = Software trap is disabled

bit 12-3 **Unimplemented:** Read as ‘0’

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

REGISTER 8-5: DMAxSTBH: DMA CHANNEL x START ADDRESS REGISTER B (HIGH)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **STB<23:16>:** Secondary Start Address bits (source or destination)

REGISTER 8-6: DMAxSTBL: DMA CHANNEL x START ADDRESS REGISTER B (LOW)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **STB<15:0>:** Secondary Start Address bits (source or destination)

12.2 Timer1 Control Register

REGISTER 12-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON(1)	—	TSIDL	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
—	TGATE	TCKPS1	TCKPS0	—	TSYNC(1)	TCS(1)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timer1 On bit(1)
1 = Starts 16-bit Timer1
0 = Stops 16-bit Timer1

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **TSIDL:** Timer1 Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as ‘0’

bit 6 **TGATE:** Timer1 Gated Time Accumulation Enable bit
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timer1 Input Clock Prescale Select bits
11 = 1:256
10 = 1:64
01 = 1:8
00 = 1:1

bit 3 **Unimplemented:** Read as ‘0’

bit 2 **TSYNC:** Timer1 External Clock Input Synchronization Select bit(1)
When TCS = 1:
1 = Synchronizes external clock input
0 = Does not synchronize external clock input
When TCS = 0:
This bit is ignored.

bit 1 **TCS:** Timer1 Clock Source Select bit(1)
1 = External clock is from pin, T1CK (on the rising edge)
0 = Internal clock (FP)

bit 0 **Unimplemented:** Read as ‘0’

Note 1: When Timer1 is enabled in External Synchronous Counter mode (TCS = 1, TSYNC = 1, TON = 1), any attempts by user software to write to the TMR1 register are ignored.

14.1 Input Capture Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

14.1.1 KEY RESOURCES

- **"Input Capture"** (DS70352) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 14-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Input Source Select for Synchronization and Trigger Operation bits[4]

`11111` = No Sync or Trigger source for ICx
`11110` = Reserved
`11101` = Reserved
`11100` = CTMU module synchronizes or triggers ICx
`11011` = ADC1 module synchronizes or triggers ICx[5]
`11010` = CMP3 module synchronizes or triggers ICx[5]
`11001` = CMP2 module synchronizes or triggers ICx[5]
`11000` = CMP1 module synchronizes or triggers ICx[5]
`10111` = Reserved
`10110` = Reserved
`10101` = Reserved
`10100` = Reserved
`10011` = IC4 module synchronizes or triggers ICx
`10010` = IC3 module synchronizes or triggers ICx
`10001` = IC2 module synchronizes or triggers ICx
`10000` = IC1 module synchronizes or triggers ICx
`01111` = Timer5 synchronizes or triggers ICx
`01110` = Timer4 synchronizes or triggers ICx
`01101` = Timer3 synchronizes or triggers ICx **(default)**
`01100` = Timer2 synchronizes or triggers ICx
`01011` = Timer1 synchronizes or triggers ICx
`01010` = PTGOx module synchronizes or triggers ICx[6]
`01001` = Reserved
`01000` = Reserved
`00111` = Reserved
`00110` = Reserved
`00101` = Reserved
`00100` = OC4 module synchronizes or triggers ICx
`00011` = OC3 module synchronizes or triggers ICx
`00010` = OC2 module synchronizes or triggers ICx
`00001` = OC1 module synchronizes or triggers ICx
`00000` = No Sync or Trigger source for ICx

Note 1: The IC32 bit in both the Odd and Even IC must be set to enable Cascade mode.
2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.
3: This bit is set by the selected input source (selected by SYNCSEL<4:0> bits). It can be read, set and cleared in software.
4: Do not use the ICx module as its own Sync or Trigger source.
5: This option should only be selected as a trigger source and not as a synchronization source.
6: Each Input Capture x (ICx) module has one PTG input source. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO8 = IC1
PTGO9 = IC2
PTGO10 = IC3
PTGO11 = IC4

NOTES:

REGISTER 24-1: PTGCST: PTG CONTROL/STATUS REGISTER (CONTINUED)

bit 1-0 **PTGITM<1:0>:** PTG Input Trigger Command Operating Mode bits(1)
- 11 = Single level detect with Step delay not executed on exit of command (regardless of the PTGCTRL command)
- 10 = Single level detect with Step delay executed on exit of command
- 01 = Continuous edge detect with Step delay not executed on exit of command (regardless of the PTGCTRL command)
- 00 = Continuous edge detect with Step delay executed on exit of command

Note 1: These bits apply to the PTGWHI and PTGWLO commands only.
2: This bit is only used with the PTGCTRL step command software trigger option.
3: Use of the PTG Single-Step mode is reserved for debugging tools only.

REGISTER 24-8: PTGC1LIM: PTG COUNTER 1 LIMIT REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC1LIM<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC1LIM<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGC1LIM<15:0>:** PTG Counter 1 Limit Register bits
May be used to specify the loop count for the `PTGJMPC1` Step command or as a limit register for the General Purpose Counter 1.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = `1` and PTGSTRT = `1`).

REGISTER 24-9: PTGHOLD: PTG HOLD REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGHOLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGHOLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGHOLD<15:0>:** PTG General Purpose Hold Register bits
Holds user-supplied data to be copied to the PTGTxLIM, PTGCxLIM, PTGSDLIM or PTGL0 registers with the `PTGCOPY` command.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = `1` and PTGSTRT = `1`).

27.5 Watchdog Timer (WDT)

For dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

27.5.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a WDT Time-out period (TWDT), as shown in Parameter SY12 in Table 30-22.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

Note: The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

27.5.2 SLEEP AND IDLE MODES

If the WDT is enabled, it continues to run during Sleep or Idle modes. When the WDT time-out occurs, the device wakes the device and code execution continues from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3,2>) needs to be cleared in software after the device wakes up.

27.5.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

27.5.4 WDT WINDOW

The Watchdog Timer has an optional Windowed mode, enabled by programming the WINDIS bit in the WDT Configuration register (FWDT<6>). In the Windowed mode (WINDIS = 0), the WDT should be cleared based on the settings in the programmable Watchdog Timer Window select bits (WDTWIN<1:0>).

FIGURE 27-2: WDT BLOCK DIAGRAM

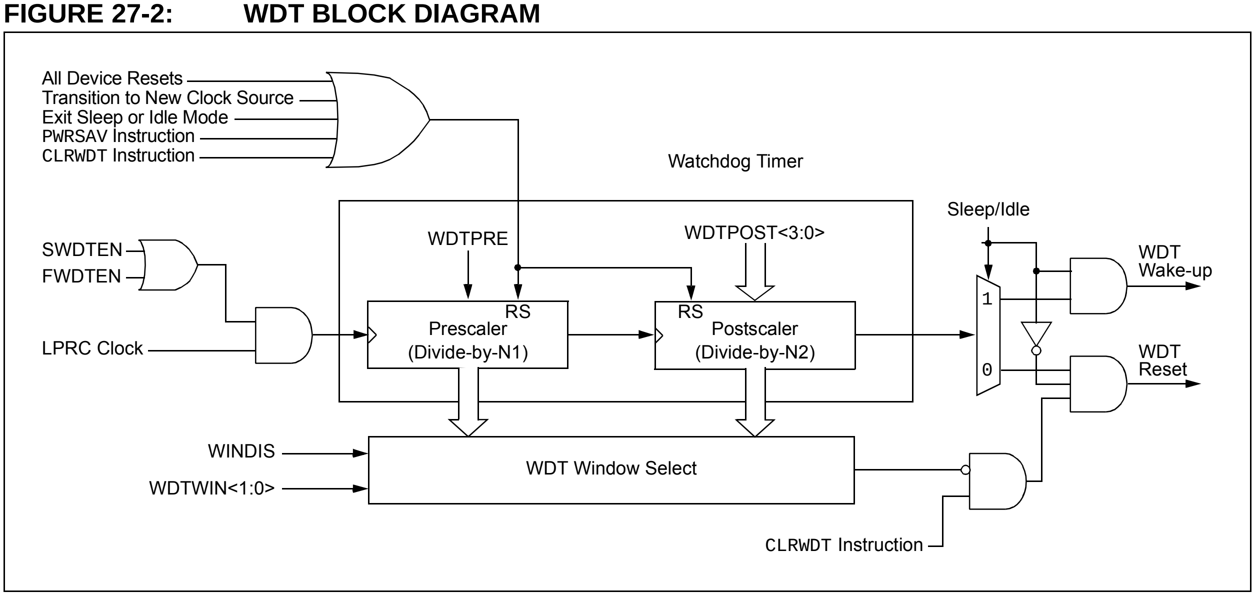


TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	I_{IL}	**Input Leakage Current**[1,2]					
DI50		I/O Pins 5V Tolerant[3]	-1	—	+1	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant[3]	-1	—	+1	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, -40°C ≤ T_A ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant[3]	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ T_A ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant[3]	-1	—	+1	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance, -40°C ≤ T_A ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant[3]	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ T_A ≤ +125°C
DI55		$\overline{MCLR}$	-5	—	+5	μA	$V_{SS} \le V_{PIN} \le V_{DD}$
DI56		OSC1	-5	—	+5	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, XT and HS modes

Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

5: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

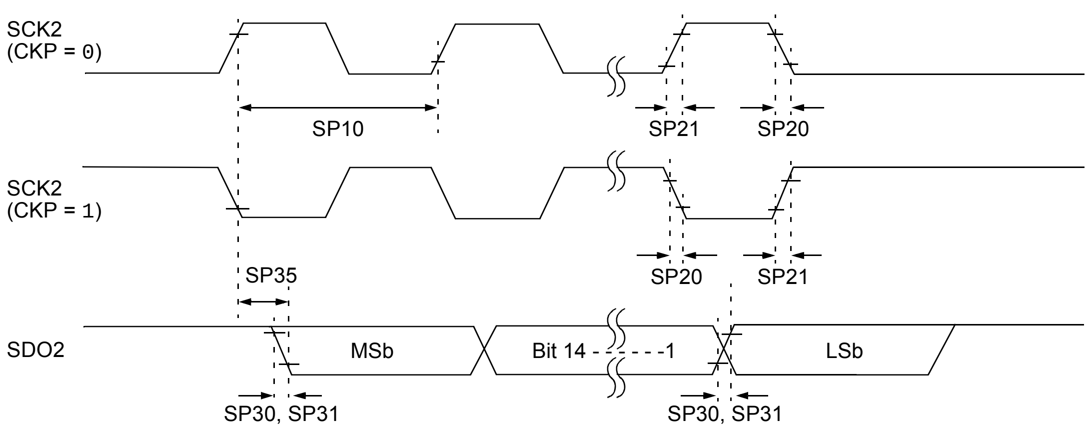
7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 30-33: SPI2 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 30-33	—	—	0,1	0,1	0,1
9 MHz	—	Table 30-34	—	1	0,1	1
9 MHz	—	Table 30-35	—	0	0,1	1
15 MHz	—	—	Table 30-36	1	0	0
11 MHz	—	—	Table 30-37	1	1	0
15 MHz	—	—	Table 30-38	0	1	0
11 MHz	—	—	Table 30-39	0	0	0

FIGURE 30-14: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-49: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(4)**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 2)	—	μs	
			400 kHz mode	TCY/2 (BRG + 2)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	μs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 2)	—	μs	
			400 kHz mode	TCY/2 (BRG + 2)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	μs	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	
			400 kHz mode	0	0.9	μs	
			1 MHz mode(2)	0.2	—	μs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 2)	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 2)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	μs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 2)	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG +2)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	μs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 2)	—	μs	
			400 kHz mode	TCY/2 (BRG + 2)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	μs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 2)	—	μs	
			400 kHz mode	TCY/2 (BRG + 2)	—	μs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	μs	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode(2)	0.5	—	μs	
IM50	CB	Bus Capacitive Loading		—	400	pF	
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	**(Note 3)**

Note 1: BRG is the value of the I²C™ Baud Rate Generator. Refer to **"Inter-Integrated Circuit (I²C™)"** (DS70330) in the "*dsPIC33/PIC24 Family Reference Manual".* Please see the Microchip web site for the latest family reference manual sections.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

4: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-32: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

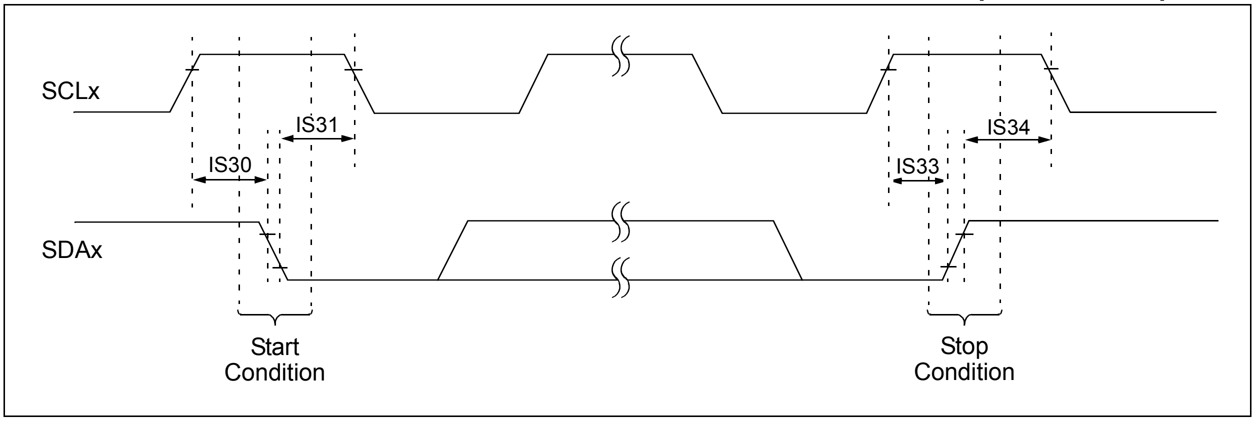
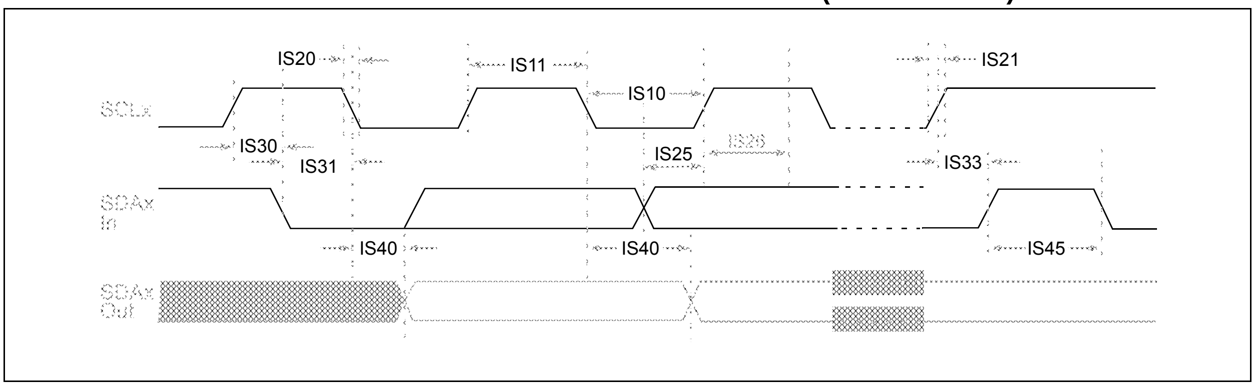


FIGURE 30-33: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)



31.1 High-Temperature DC Characteristics

TABLE 31-1: OPERATING MIPS VS. VOLTAGE

Characteristic	V_{DD} Range (in Volts)	Temperature Range (in °C)	Max MIPS
			dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X
HDC5	3.0 to 3.6V(1)	-40°C to +150°C	40

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$. Analog modules, such as the ADC, may have degraded performance. Device functionality is tested but not characterized.

TABLE 31-2: THERMAL OPERATING CONDITIONS

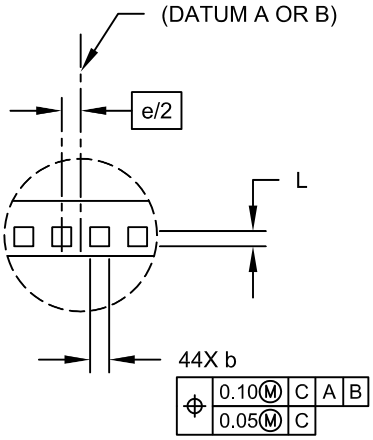
Rating	Symbol	Min	Typ	Max	Unit
High-Temperature Devices					
Operating Junction Temperature Range	T_J	-40	—	+155	°C
Operating Ambient Temperature Range	T_A	-40	—	+150	°C
Power Dissipation: Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $I/O = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 31-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

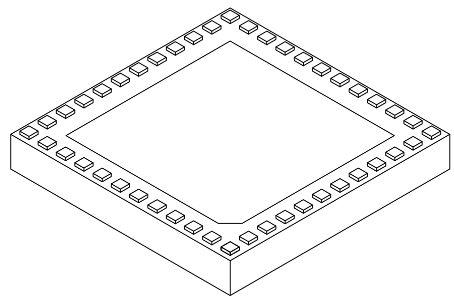
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +150°C				
Parameter No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
Operating Voltage							
HDC10	**Supply Voltage**						
	V_{DD}	—	3.0	3.3	3.6	V	-40°C to +150°C

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Number of Pins per Side	ND		12	
Number of Pins per Side	NE		10	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2